

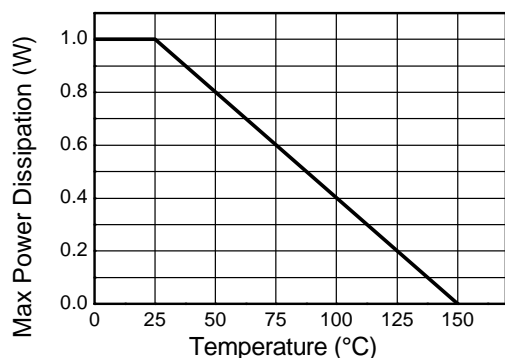
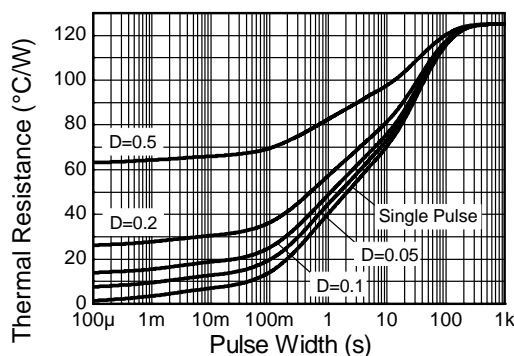
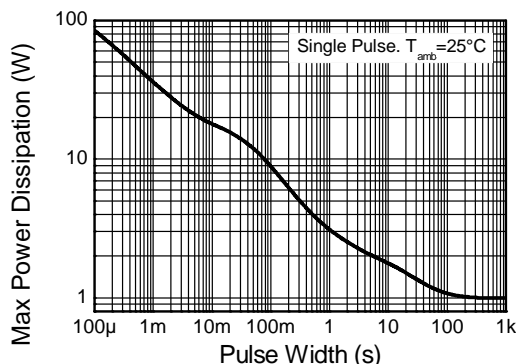
**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	50	V
Emitter-Base Voltage	V <sub>EBO</sub>	7	V
Continuous Collector Current	I <sub>C</sub>	3	A
Peak Pulse Current	I <sub>CM</sub>	6	A
Base Current	I <sub>B</sub>	500	mA

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	1	W
		2	
Thermal Resistance, Junction to Ambient Air	R <sub>θJA</sub>	125	°C/W
		62.5	
Thermal Resistance, Junction to Leads	R <sub>θJL</sub>	5.73	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

- Notes:
- For a device surface mounted on 15mm x 15mm x 0.6mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in steady state condition.
  - Same as note (5), except the device is mounted on 40mm x 40mm x 1.6mm FR4 PCB
  - Thermal resistance from junction to solder-point (on the exposed collector pad).

**Thermal Characteristics and Derating Information**

**Derating Curve**

**Transient Thermal Impedance**

**Pulse Power Dissipation**

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CB0</sub>	60	—	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	50	—	—	V	I <sub>C</sub> = 10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	7	—	—	V	I <sub>E</sub> = 100μA
Collector Cutoff Current	I <sub>CBO</sub>	—	—	100	nA	V <sub>CB</sub> = 60V
Emitter Cutoff Current	I <sub>EBO</sub>	—	—	100	nA	V <sub>EB</sub> = 5.6V
DC Current Transfer Static Ratio (Note 8)	h <sub>FE</sub>	82 45	—	270 —	—	I <sub>C</sub> = 500mA, V <sub>CE</sub> = 2V I <sub>C</sub> = 1.5A, V <sub>CE</sub> = 2V
Collector-Emitter Saturation Voltage (Note 8)	V <sub>CE(sat)</sub>	—	105	350	mV	I <sub>C</sub> = 1A, I <sub>B</sub> = 50mA
Transitional Frequency	f <sub>T</sub>	—	180	—	MHz	I <sub>C</sub> = 100mA, V <sub>CE</sub> = 2V f = 1MHz
Output Capacitance	C <sub>obo</sub>	—	17	—	pF	V <sub>CB</sub> = 10V, f = 1MHz,

Note: 8. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

## Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

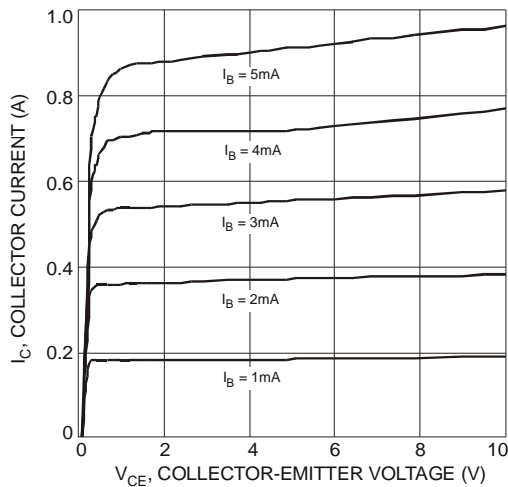


Figure 1 Typical Collector Current vs. Collector-Emitter Voltage

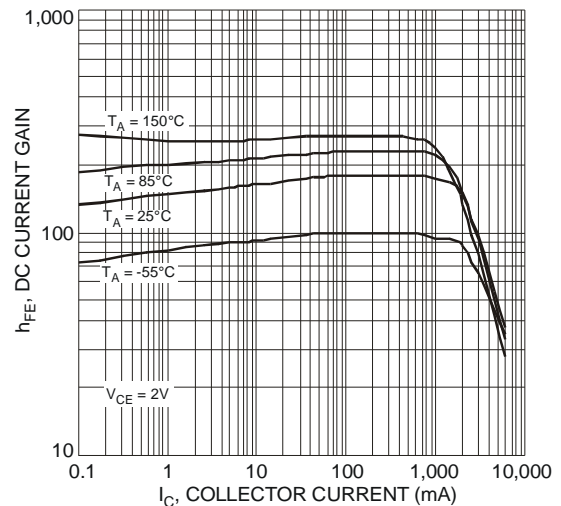


Figure 2 Typical DC Current Gain vs. Collector Current

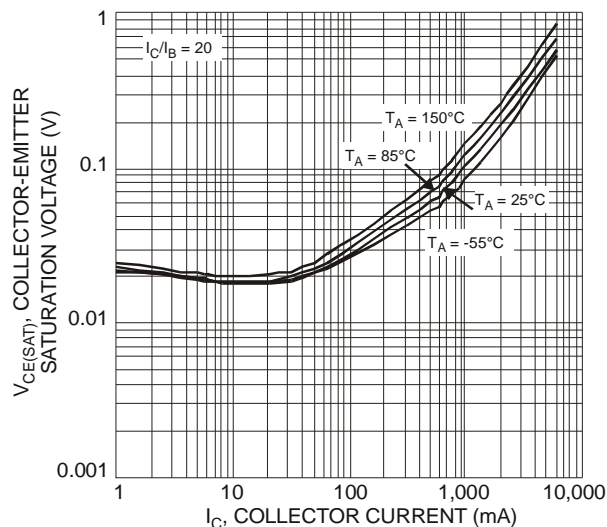


Figure 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current

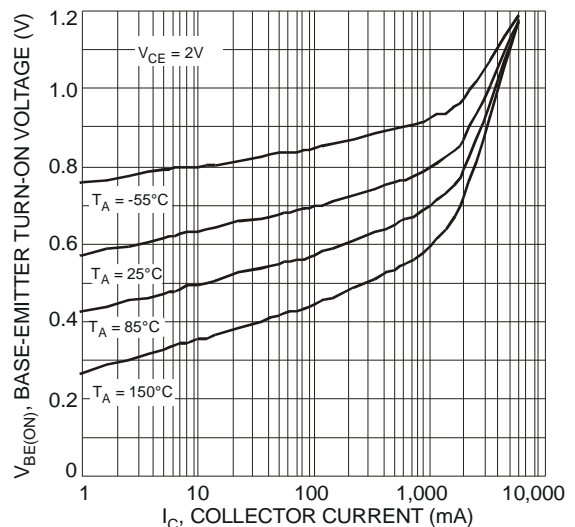


Figure 4 Typical Base-Emitter Turn-On Voltage vs. Collector Current

**Typical Electrical Characteristics (cont.)**

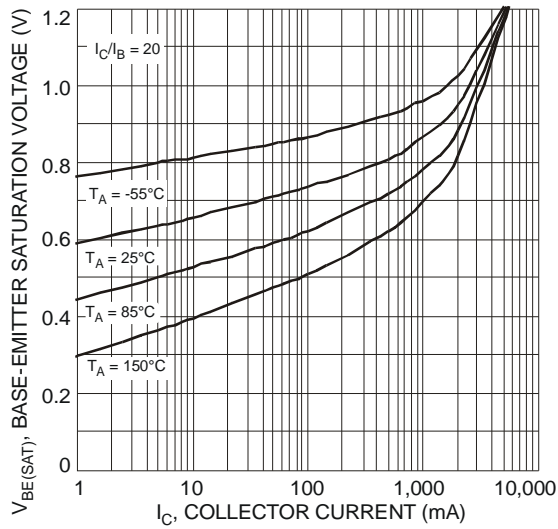


Figure 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

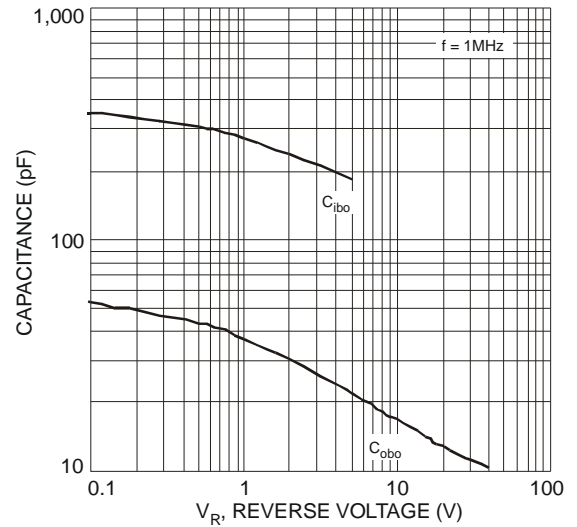


Figure 6 Typical Capacitance Characteristics

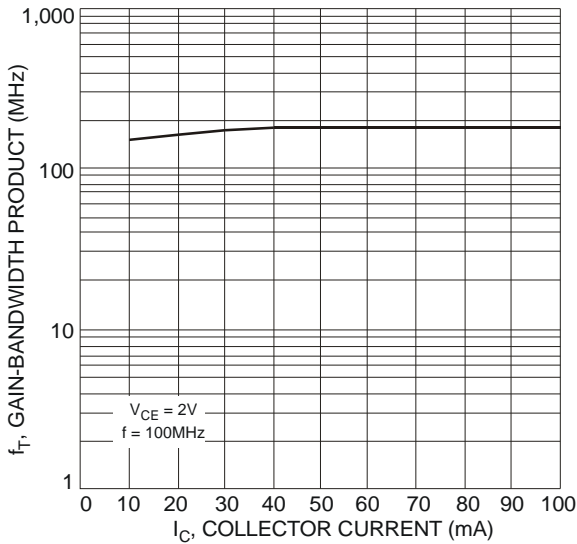
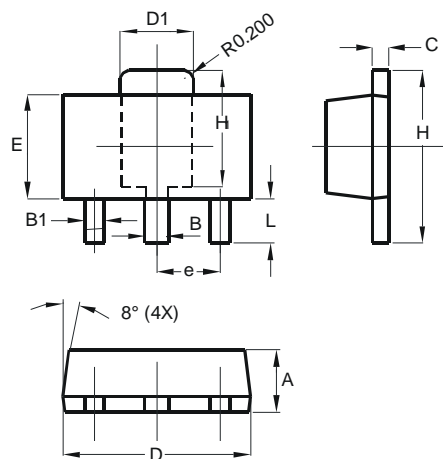


Figure 7 Typical Gain-Bandwidth Product vs. Collector Current

## Package Outline Dimensions

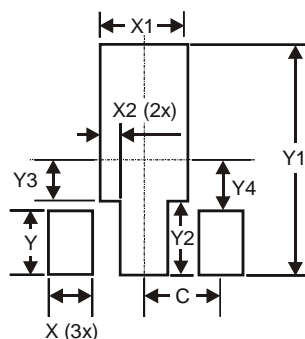
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.44
D	4.40	4.60
D1	1.62	1.83
E	2.29	2.60
e	1.50 Typ	
H	3.94	4.25
H1	2.63	2.93
L	0.89	1.20
All Dimensions in mm		

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

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